

# PATENT ABSTRACTS OF JAPAN

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(71)Applicant : SEIKO EPSON CORP

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(72)Inventor : KAWAGUCHI YOSHITO

## (54) CIRCUIT MODULE

(57)Abstract:

**PURPOSE:** To obtain a circuit module which does not induce pattern burn-out due to stress in assembly, etc., by providing a pattern which is related to a signal line at a flexible printed-circuit board and that which is not related to the signal line at a printed-circuit board of a circuit module opposing it, and then soldering the patterns.

**CONSTITUTION:** Corresponding signal lines of signal line patterns 3 are soldered on a printed-circuit board 1 and a flexible circuit board 2.

Further, patterns 4 which are not related to the signal line are also soldered. The patterns which are not related to the signal line are located at an inside from a part which is exposed from a protection film 5 of the signal line pattern 3.

When the flexible printed-circuit board 2 is soldered onto the printed-circuit board 1, soldering of the signal line pattern is made at an inside from the printed-circuit board end face as

compared with soldering of a pattern which is not related to the signal line. Therefore, if a stress is applied in a direction for releasing the flexible printed-circuit board 2 from the printed-circuit board 1, stress is applied to a part to be soldered of the pattern 4 which is not related to the signal line and no stress is applied to the part to be soldered of the signal line pattern 3.

